

N-Channel Enhancement Mode Field Effect Transistor

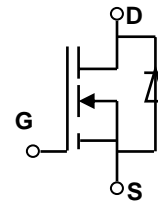
FEATURES

- Super high dense cell design for low $R_{DS(ON)}$
- Rugged and reliable
- Simple drive requirement
- SOT-23 package

PRODUCT SUMMARY		
V_{DSS}	I_D	$R_{DS(ON)}$ (m Ω) Typ
30V	2.5A	70 @ $V_{GS}=10V$
		105 @ $V_{GS}=4.5V$



NOTE: The MT3402 is available in a lead-free package



ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	20	V
Drain Current-Continuous ^a @ $T_j=125^\circ C$	I_D	2.5	A
	I_{DM}	10	A
- Pulse d^b			
Drain-source Diode Forward Current ^a	I_S	1.25	A
Maximum Power Dissipation ^a	P_D	1.25	W
Operating Junction and Storage Temperature Range	T_j, T_{STG}	-55 to 150	$^\circ C$

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to Ambient ^a	$R_{th JA}$	100	$^\circ C/W$
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ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise noted)

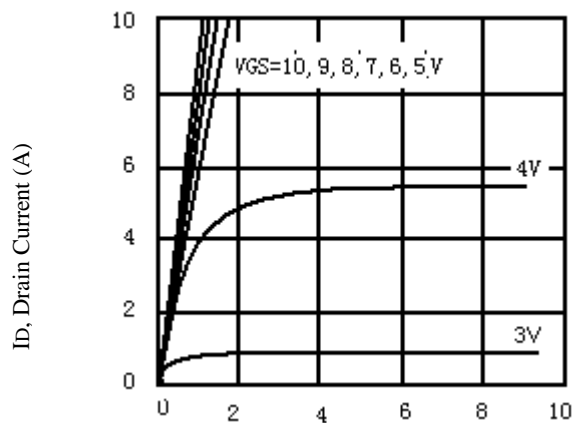
Parameter	Symbol	Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =16V, V _{GS} =0V			1	μA
Gate Leakage Current	I _{GSS}	V _{GS} =20V, V _{DS} =0V			100	nA
ON CHARACTERISTICS						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.0		3.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =2.5A		55	70	mΩ
		V _{GS} =4.5V, I _D =2.0A		80	105	
Forward Transconductance	g _{fs}	V _{DS} =4.5V, I _D =2.5A		4.6		S
DAYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iSS}	V _{DS} =10V, V _{GS} =0V f=1.0MHz		240		pF
Output Capacitance	C _{oSS}			110		pF
Reverse Transfer Capacitance	C _{rSS}			17		pF
SWITCHING CHARACTERISISTICS						
Turn-On Delay Time	t _{d(ON)}	V _{DD} =15V I _D =1.0A, V _{GEN} =10V R _L =15Ω R _G =6Ω		8	20	ns
Rise Time	t _r			12	30	ns
Turn-Off Delay Time	t _{d(off)}			17	35	ns
Fall Time	t _f			8	20	ns
Total Gate Charge	Q _g	V _{DS} =15V, I _D =2.5A V _{GS} =4.5V		4.5	10	nC
Gate-Source Charge	Q _{gs}			0.8		nC
Gate-Drain Charge	Q _{gd}			1.0		nC

ELECTRICAL CHARACTERICS (TA=25°C unless otherwise noted)

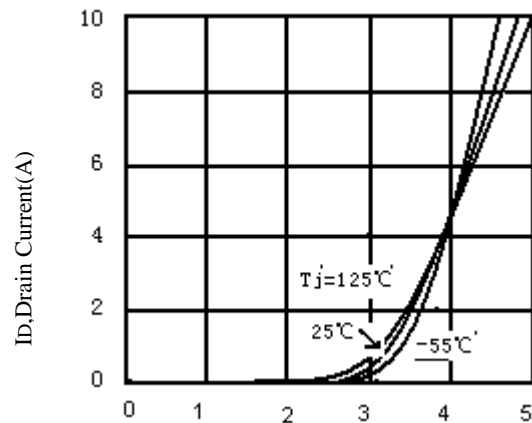
Parameter	Symbol	Condition	Min	Typ	Max	Unit
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage	VSD	VGS=0V,Is=1.25A		0.77	1.2	V

Notes

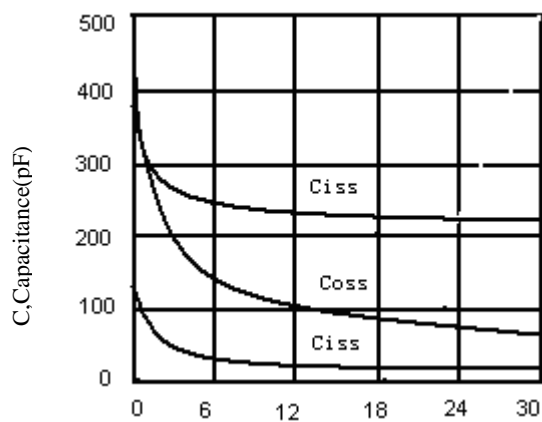
- a. Surface Mounted on FR4 Board, $t \leq 10\text{sec}$
- b. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 2\%$
- c. Guaranteed by design, not subject to production testing.



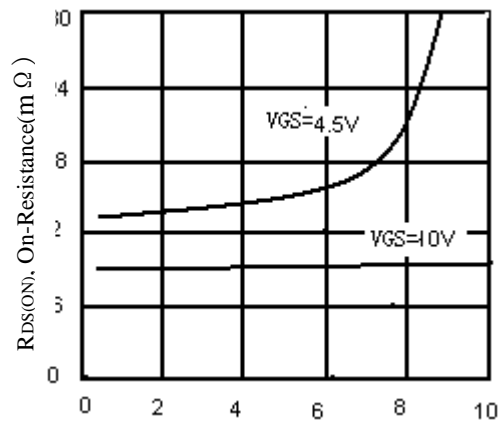
V_{DS}, Drain-to-Source Voltage (V)
Figure 1. Output Characteristics



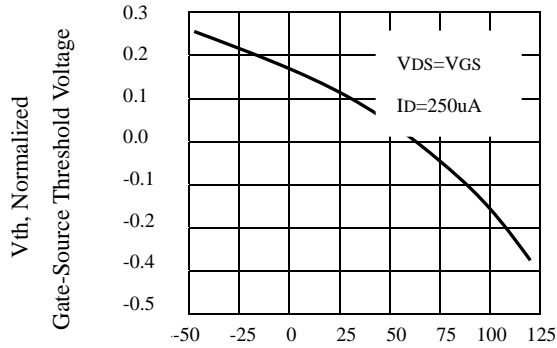
V_{GS}, Gate-to-source Voltage (V)
Figure 2. Transfer Characteristics



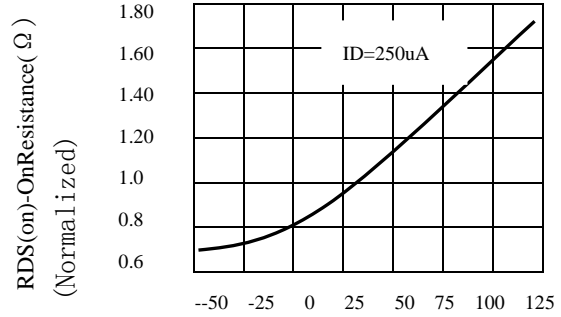
V_{GS}, Drain-to Source Voltage
Figure3. Capacitance



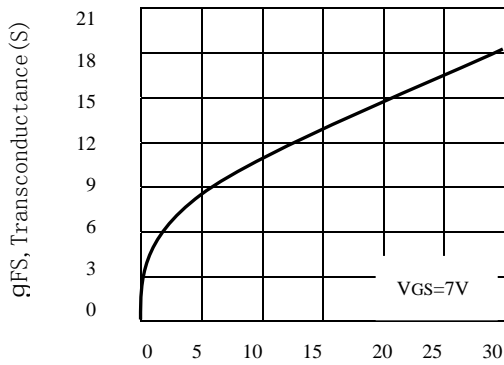
I_D -DrainCurrent (A)



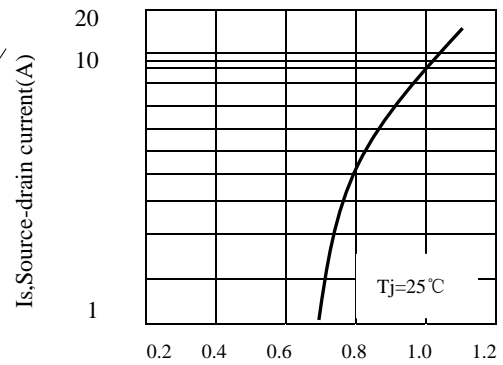
Tj, Junction Temperature(°C)
Figure5. Gate Threshold Variation
With Temperature



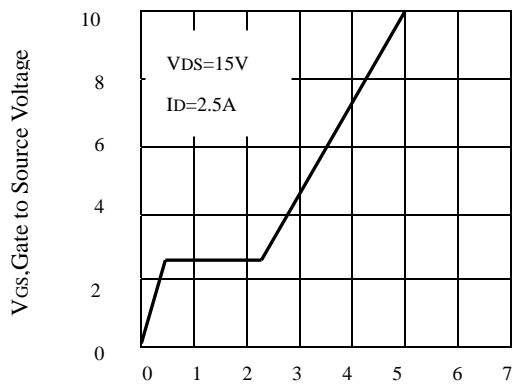
Tj, Junction Temperature (°C)
Figure6. Breakdown Voltage Variation
With Temperature



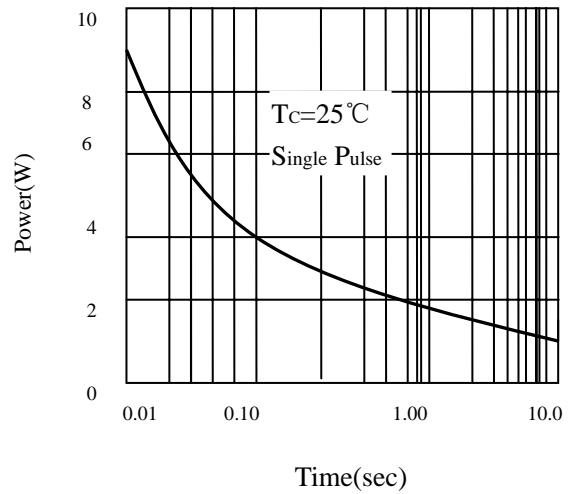
Ids, Drain-Source Current (A)
Figure7. Transconductance Variation
With Drain Current



VSD, Body Diode Forward Voltage
Figure8. Body Diode Forward Voltage

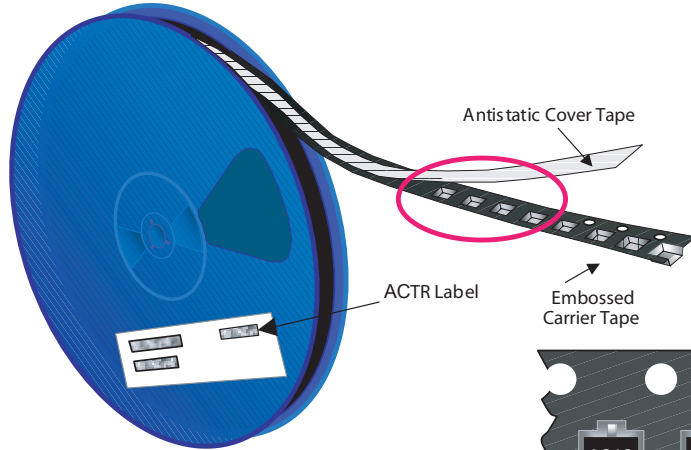


Qg, Total Gate Charge (nC)
Figure9. Gate Charge



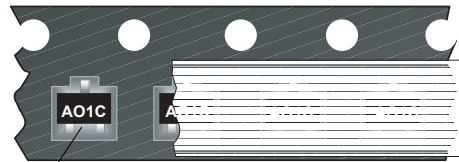
SOT-23 Std Tape and Reel Data

SOT23-3L Packaging Configuration: Figure 1.0

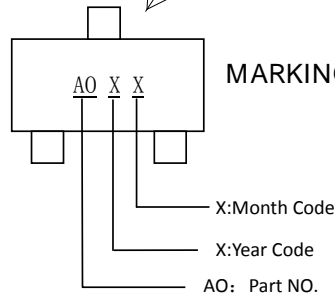


Packaging Description:
 SOT23-3L parts are shipped in tape. The carrier tape is made from a dissipative (carbon filled) polycarbonate resin. The cover tape is a multilayer film (Heat Activated Adhesive in nature) primarily composed of polyester film, adhesive layer, sealant, and anti-static sprayed agent. These reeled parts in standard option are shipped with 3,000 units per 7" or 177mm diameter reel. The reels are dark blue in color and is made of polystyrene plastic (anti-static coated). Other option comes in 10,000 units per 13" or 330cm diameter reel. This and some other options are described in the Packaging Information table.
 These full reels are individually labeled and placed inside a standard immediate box made of recyclable corrugated brown paper with a Fairchild logo printing. One box contains five reels maximum. And these immediate boxes are placed inside a labeled shipping box which comes in different sizes depending on the number of parts shipped.

SOT23-3L Packaging Information		
Packaging Option	Standard (no flow code)	D87Z
Packaging type	TNR	TNR
Qty per Reel/Tube/Bag	3,000	10,000
Reel Size	7" Dia	13"
Box Dimension (mm)	193x183x80	355x333x40
Max qty per Box	15,000	30,000
Weight per unit (gm)	0.0082	0.0082
Weight per Reel (kg)	0.1175	0.4006
Note/Comments		

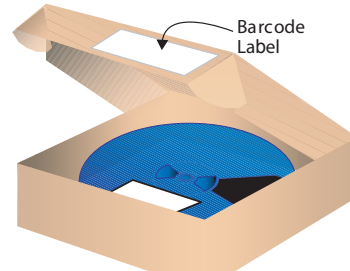


SOT23-3L Unit Orientation



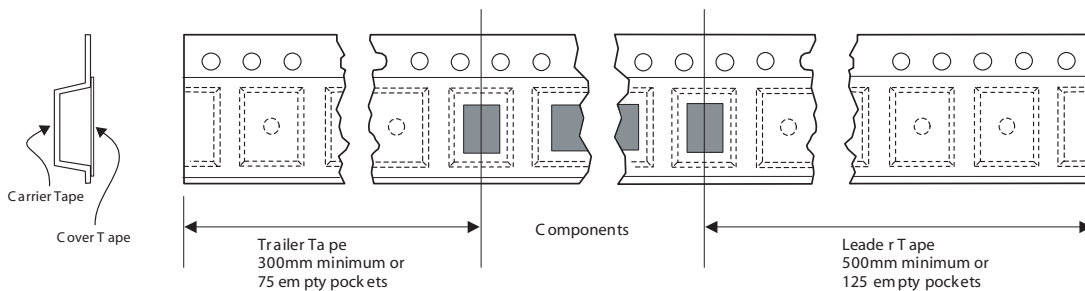
MARKING DIAGRAM

Barcode Label sample



193mm x 183mm x 80mm Pizza Box for Standard Option

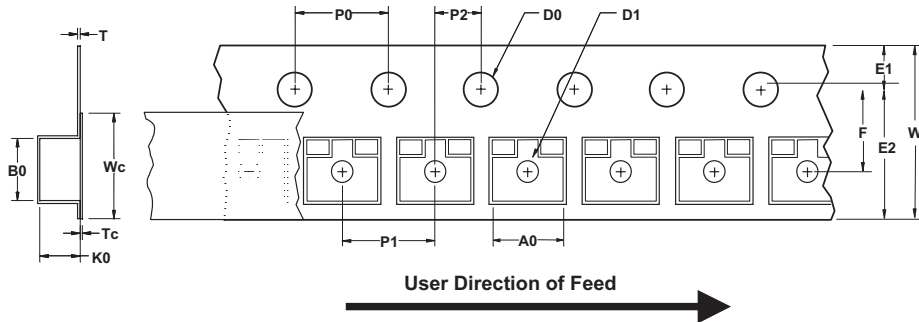
SOT23-3L Tape Leader and Trailer Configuration: Figure 2.0



SOT-23 Std Tape and Reel Data, continued

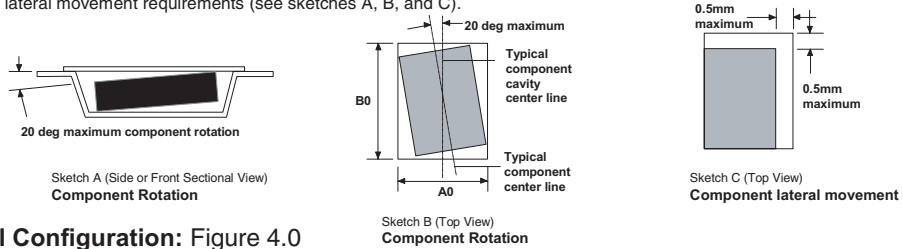


SOT23-3L Embossed Carrier Tape Configuration: Figure 3.0

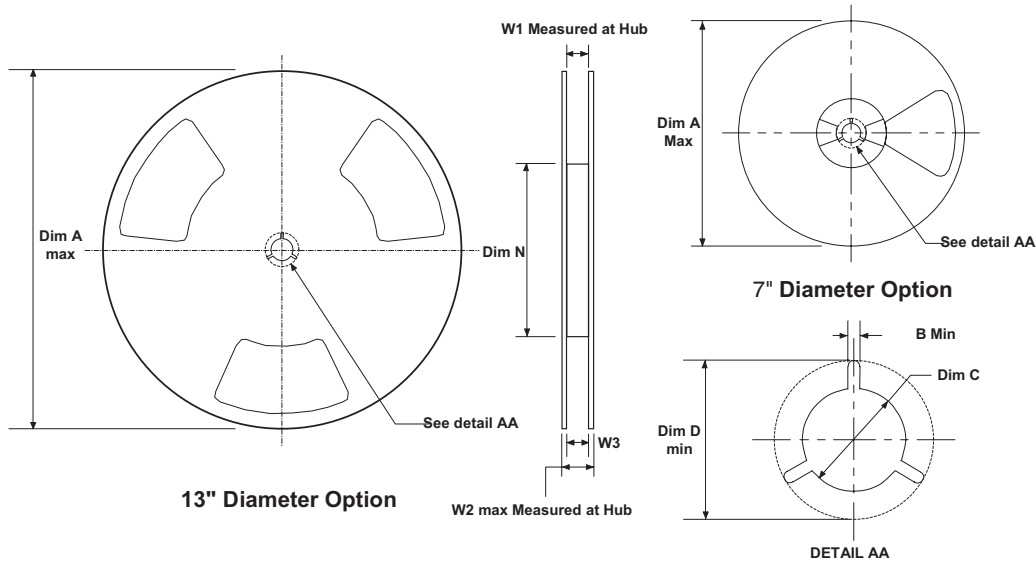


Dimensions are in millimeter														
Pkg type	A0	B0	W	D0	D1	E1	E2	F	P1	P0	K0	T	Wc	Tc
SOT-23 (8mm)	3.15 +/-0.10	2.77 +/-0.10	8.0 +/-0.3	1.55 +/-0.05	1.125 +/-0.125	1.75 +/-0.10	6.25 min	3.50 +/-0.05	4.0 +/-0.1	4.0 +/-0.1	1.30 +/-0.10	0.228 +/-0.013	5.2 +/-0.3	0.06 +/-0.02

Notes: A0, B0, and K0 dimensions are determined with respect to the EIA/Jedec RS-481 rotational and lateral movement requirements (see sketches A, B, and C).



SOT23-3L Reel Configuration: Figure 4.0



Dimensions are in inches and millimeters									
Tape Size	Reel Option	Dim A	Dim B	Dim C	Dim D	Dim N	Dim W1	Dim W2	Dim W3 (LSL-USL)
8mm	7" Dia	7.00 177.8	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	2.165 55	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9
8mm	13" Dia	13.00 330	0.059 1.5	512 +0.020/-0.008 13 +0.5/-0.2	0.795 20.2	4.00 100	0.331 +0.059/-0.000 8.4 +1.5/0	0.567 14.4	0.311 - 0.429 7.9 - 10.9



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